TI LaunchPad™ kit with SimpleLink™ Wireless MCU
Microcontroller development kit for rapid prototyping featuring the CC1352P microcontroller

PART NO: LAUNCHXL-CC1352P-2

LAUNCH YOUR DESIGN

START @
Dev.ti.com/launchxl-cc1352p-2
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- Pin aligns with LaunchPad pinout standard.

Explore all TI LaunchPad™ kits @ www.ti.com/launchpad

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